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(54) **STRESS RELIEF FOR FLIP-CHIP
PACKAGED DEVICES**

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(57) **ABSTRACT**

In a described example, an apparatus includes: a package
substrate having a planar die mount surface; recesses
extending into the planar die mount surface; and a semicon-
ductor device die flip chip mounted to the package substrate
on the planar die mount surface, the semiconductor device
die having post connects having proximate ends on bond
pads on an active surface of the semiconductor device die,
and extending to distal ends away from the semiconductor
device die having solder bumps, wherein the solder bumps
form solder joints to the package substrate within the
recesses.

